

#### 30V N-Channel Enhancement Mode MOSFET

Voltage 30 V Current 300mA

#### **Features**

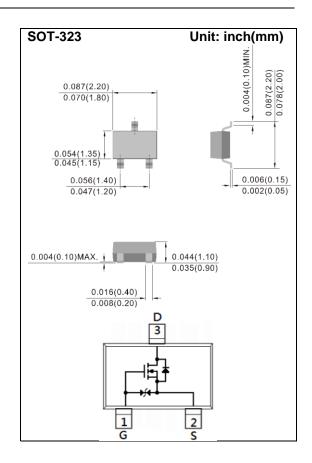
- Advanced Trench Process Technology
- ESD Protected
- Specially Designed for Relay driver, Speed line drive, etc
- Lead free in compliance with EU RoHS 2.0
- Green molding compound as per IEC61249 standard

#### **Mechanical Data**

• Case: SOT-323 Package

• Terminals : Solderable per MIL-STD-750, Method 2026

• Approx. Weight: 0.00018 ounces, 0.005 grams



### Maximum Ratings and Thermal Characteristics (T<sub>A</sub>=25°C unless otherwise noted)

PARAMETER		SYMBOL	LIMIT	UNITS	
Drain-Source Voltage		V <sub>DS</sub>	30	V	
Gate-Source Voltage		V <sub>G</sub> s	<u>+</u> 10		
Continuous Drain Current (Note 4)		I <sub>D</sub>	300	mA	
Pulsed Drain Current (Note 1)		I <sub>DM</sub>	600		
Power Dissipation	T <sub>A</sub> =25°C	$P_{D}$	350	mW	
	Derate above 25°C		2.8	mW/°C	
Operating Junction and Storage Temperature Range		T <sub>J</sub> ,T <sub>STG</sub>	-55~150	°C	
Typical Thermal Resistance					
- Junction to Ambient (Note 3,4)		Reja	357	°C/W	



## Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)

PARAMETER	SYMBOL TEST CONDITION		MIN.	TYP.	MAX.	UNITS	
Static							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	$V_{GS}=0V, I_{D}=250uA$		-	-		
Gate Threshold Voltage	$V_{GS(th)}$	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA	0.4	0.75	1	V	
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =300mA	-	0.7	1.2	Ω	
		V <sub>GS</sub> =2.5V, I <sub>D</sub> =200mA	-	0.8	1.6		
		V <sub>GS</sub> =1.8V, I <sub>D</sub> =100mA	-	0.9	2		
		V <sub>GS</sub> =1.5V, I <sub>D</sub> =50mA	-	1.1	3		
		V <sub>GS</sub> =1.2V, I <sub>D</sub> =20mA	-	1.5	4		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =24V, V <sub>GS</sub> =0V	-	-	1	uA	
Gate-Source Leakage Current	Igss	V <sub>GS</sub> = <u>+</u> 8V, V <sub>DS</sub> =0V	-	-	<u>+</u> 10		
Dynamic (Note 5)							
Total Gate Charge	$Q_g$	\/ 40\/   000 A	-	0.9	-	nC	
Gate-Source Charge	$Q_gs$	$V_{DS}=10V, I_{D}=300mA, V_{GS}=4.5V$	-	0.3	-		
Gate-Drain Charge	$Q_{gd}$	VGS=4.5 V	-	0.2	-		
Input Capacitance	Ciss	\/ 40\/ \/ 0\/	-	45	-	pF	
Output Capacitance	Coss	V <sub>DS</sub> =10V, V <sub>GS</sub> =0V, f=1MHZ	-	14	-		
Reverse Transfer Capacitance	Crss	I=IIVIDZ	-	0.8	-		
Turn-On Delay Time	td <sub>(on)</sub>	\/ 40\/ I 200~ A	-	8.3	-		
Turn-On Rise Time	tr	V <sub>DD</sub> =10V, I <sub>D</sub> =300mA,	-	5.7	-	ns	
Turn-Off Delay Time	td <sub>(off)</sub>	V <sub>GS</sub> =4V, R <sub>G</sub> =10Ω (Note 1,2)	-	35	-		
Turn-Off Fall Time	tf	RG=1002 (Note 1,2)	-	12	-		
Drain-Source Diode							
Maximum Continuous Drain-Source Diode Forward Current	ls			-	300	mA	
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =300mA, V <sub>GS</sub> =0V	-	0.9	1.3	V	

#### NOTES:

- 1. Pulse width < 300us, Duty cycle < 2%.
- 2. Essentially independent of operating temperature typical characteristics.
- 3. Rejah is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins mounted on a 1 inch FR-4 with 2oz. square pad of copper.
- 4. The maximum current rating is package limited.
- 5. Guaranteed by design, not subject to production testing.



#### **TYPICAL CHARACTERISTIC CURVES**

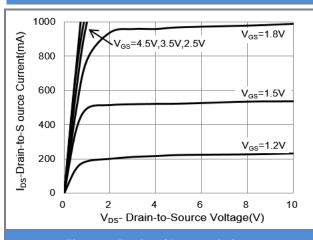


Fig.1 On-Region Characteristics

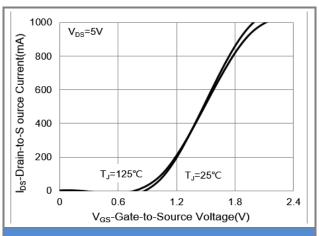


Fig.2 Transfer Characteristics

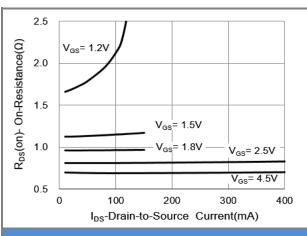


Fig.3 On-Resistance vs. Drain Current

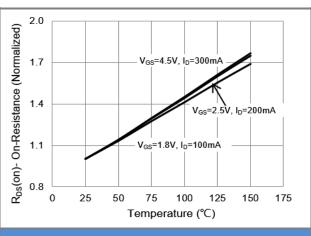
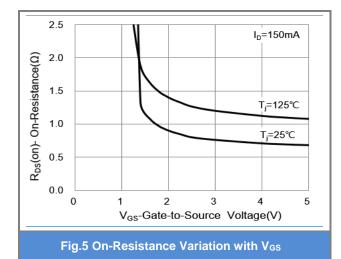
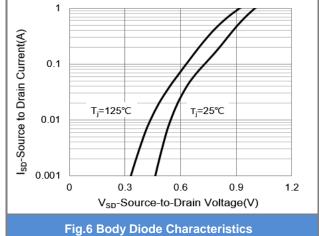


Fig.4 On-Resistance vs. Junction temperature





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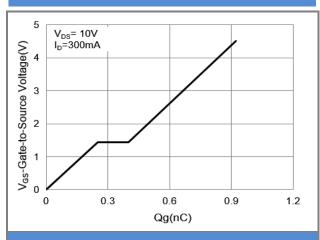


Fig.7 Gate-Charge Characteristics

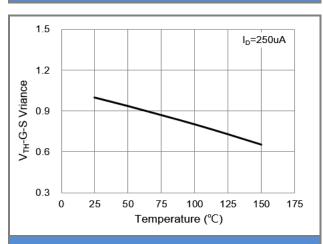


Fig.9 Threshold Voltage Variation with Temperature

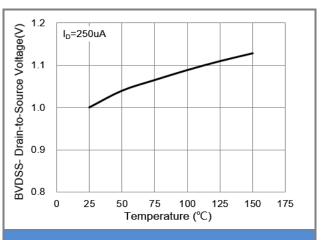


Fig.8 Breakdown Voltage Variation vs. Temperature

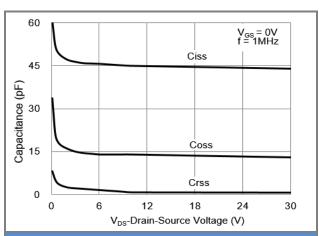


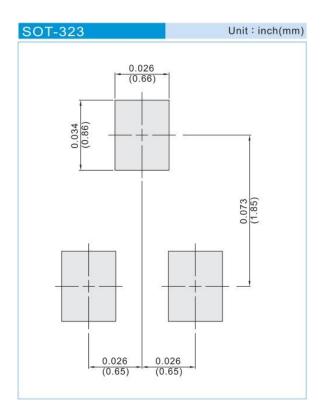
Fig.10 Capacitance vs. Drain-Source Voltage



## **Product and Packing Information**

Part No.	Package Type	Packing Type	Marking
PJC7428	SOT-323	3K pcs / 7" reel	C28

## **Mounting Pad Layout**





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